

**RECESS REDUCTION FOR LEAKAGE
IMPROVEMENT IN HIGH DENSITY CAPACITORS**

ABSTRACT OF THE DISCLOSURE

The present invention provides a capacitor [205]. The capacitor [205] includes a first conductive layer [206] located on an interconnect structure [226] formed in a dielectric layer [228], a capacitor dielectric layer [208] located over the first conductive layer [206] and a second conductive layer [210] located over the capacitor dielectric layer [208]. The recess relief in the surface of the dielectric layer [228] attributable to a fabrication process has been reduced about the interconnect structure [226] to provide a more planar deposition surface over which the capacitor's [205] layers may be deposited.